IN THE CLAIMS:

Claims 1-14 (Canceled)

15. (Currently amended) A radiation-sensitive resin composition comprising:

water,

a water-soluble resin dissolved in the water,

an acid former, in the form of solid particles having an average particle diameter of 1.5 μm or less and dispersed in the water, said acid former generating an acid when irradiated with activation energy,

a spectrum sensitizer, in the form of solid particles of an electron donor having an average particle diameter of 1.5 μm or less and dispersed in the water, for sensitizing the acid generation by the acid former by absorption of light, and

an acid-reactive insolubilizing agent dissolved or dispersed in the water for converting the water-soluble resin into an insoluble form in the presence of said acid.

16. (Previously presented) The composition as recited in claim 15, further comprising a compound having at least one radically polymerizable unsaturated bond and dissolved or dispersed in the water.

17. (Previously presented) The composition as recited in claim 15, wherein said acid-reactive insolubilizing agent is an N-methylolated or N-alkoxymethylated nitrogen-containing compound, a hydroxymethylated phenol derivative or a resol resin.

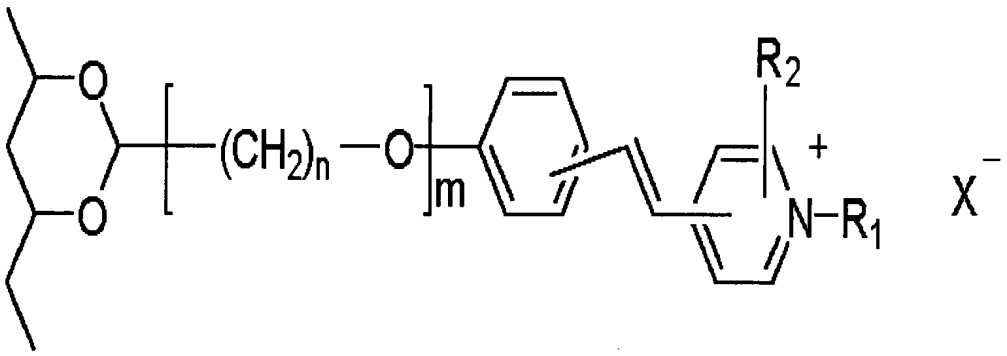
18. (Previously presented) The composition as recited in claim 15, wherein said acid-reactive insolubilizing agent is a compound having at least one epoxy group, oxetane group, vinyloxy group, isopropenyloxy group or orthoester group.

19. (Previously presented) The composition as recited in claim 15, wherein said acid-reactive insolubilizing agent has at least one formyl group.

20. (Previously presented) The composition as recited in claim 15, further comprising an aqueous emulsion of a hydrophobic polymer.

21. (Previously presented) The composition as recited in claim 15, further comprising a water-soluble, photo-insolubilizable resin.

22. (Previously presented) The composition as recited in claim 21, wherein said water-soluble, photo-insolubilizable resin is a photo-crosslinkable polyvinyl alcohol containing a styrylpyridinium group represented by the following formula (1):



wherein R_1 represents a hydrogen atom, an alkyl group or an aralkyl group, R_2 represents a hydrogen atom or a lower alkyl group, X^- represents a halogen ion, a phosphate ion, a p-toluenesulfonate ion or a mixture of these anions, m is a number of 0 or 1 and n is an integer of 1 to 6.

23. (Previously presented) The composition as recited in claim 21, wherein said water-soluble, photo-insolubilizable resin comprises poly(vinyl alcohol), casein or gelatin, and a water-soluble diazo resin or a dichromate.

24. (Previously presented) The composition as recited in claim 15, wherein said acid-reactive insolubilizing agent is present in an amount of 5 to 1,000 parts by

weight per 100 parts by weight of said water-soluble resin, said acid former is present in an amount of 1 to 100 parts by weight per 100 parts by weight of said acid-reactive insolubilizing agent, and said sensitizer is present in an amount of 5 to 100 parts by weight per 100 parts by weight of said acid former.

25. (Canceled)

26. (Previously presented) A radiation-sensitive resin film obtained by drying a layer of the composition according to claim 15.

27. (Canceled)

28. (Previously presented) A pattern forming method comprising the steps of:

irradiating a radiation sensitive resin film according to claim 26 with activation energy, and

developing the irradiated film with water.

29. (Previously presented) A pattern forming method as recited in claim 28, further comprising heating the irradiated film before said developing with water.

30. (Canceled)

31. (Canceled)

32. (Previously presented) The composition as recited in claim 15 wherein said water is the only solvent.

33. (Previously presented) The composition as recited in claim 15 which is developable with neutral water.

34. (Canceled)

35. (Previously presented) The composition as recited in claim 32 which is developable with neutral water.

36. (Previously presented) The composition as recited in claim 15 wherein the pH of the solution of water-soluble resin in water is about 7.